

07-15-2003



102497165

COVER SHEET  
BY

Attorney Docket No.: 053933-5046

To the Commissioner for Patents

ATTN: MAIL STOP ASSIGNMENT RECORDATION SERVICES

Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

7-1-03

- 1. Jong-Jin LEE
- 2. Young-Hwan SHIN

Additional names of conveying party(ies) attached?

☐ Yes ☒ No

2. Name and address of receiving party(ies):

Name: Samsung Electro-Mechanics Co., Ltd.

Internal Address:

Street Address: 314, Maetan-3dong, Paldal-gu, Suwon-si,  
Kyunggi-do 442-743, Republic of Korea

City:

State:

Zip:

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
- ☐ Security Agreement ☐ Change of Name
- ☐ Other

Execution Date: June 10, 2003

Additional name(s) & address(es) attached?

☐ Yes ☒ No

4. New Application number(s) or patent number(s): NEW APPLICATION

10609499

If this document is being filed together with a new application the execution date of the application is:

June 10, 2003

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached: ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Robert J. Gaybrick

Internal Address: Morgan, Lewis & Bockius LLP  
Customer No. 09629

Street Address: 1111 Pennsylvania Ave., N.W.  
City: Washington State: D.C. Zip: 20004

6. Total number of applications and patents involved: 1

7. Total fee (37 C.F.R. §3.41): \$40.00

☒ Authorized to be charged to Deposit Account 50-0310

8. Deposit Account No. 50-0310

(Attach duplicate page if paying by deposit account)

9. Statement and Signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Robert J. Goodell Reg. No. 41,040

Name of Person Signing

Signature

July 1, 2003

Date

Total number of pages including cover sheet, attachments and documents: 3

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## ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

### PACKAGE SUBSTRATE MANUFACTURED USING ELECTROLYTIC LEADLESS PLATING PROCESS, AND METHOD FOR MANUFACTURING THE SAME

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on \_\_\_\_\_, (Application No. \_\_\_\_\_); and

WHEREAS, **Samsung Electro-Mechanics Co., Ltd.**, a corporation of Korea, whose post office address is **314, Maetan-3dong, Paldal-gu, Suwon-si, Kyunggi-do 442-743, Republic of Korea** (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

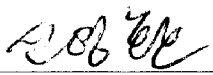
NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all division s, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. \_\_\_\_\_, filed \_\_\_\_\_) the filing date and application number of said application when known. **July 1, 2003**

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s):

Full Name of Sole or First Assignor <b>Jong-Jin LEE</b>	Assignor's Signature <i>Lee Jong-Jin</i>	Date <i>June 10, 2003</i>
Address <b>305-1804, Seonbimaecul 3-Danji Apt., Songchon-dong, Daedeok-gu, Daejeon 306-777, Korea</b>		Citizenship <b>KOREA</b>
Names of additional inventors attached <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No		

Full Name of Sole or First Assignor <b>Young-Hwan SHIN</b>	Assignor's Signature 	Date <i>June 10 2003</i>
Address <b>510-704, Expo Apt., Jeonmin-dong, Yuseong-gu, Daejeon 305-762, Korea</b>		Citizenship <b>KOREA</b>
Names of additional inventors attached <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		